

As a below-named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name: that I verily believe I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought in the application entitled:

SEMICONDUCTOR PACKAGE AND METHOD FOR PRODUCING HEAT-RADIATING SUBSTRATE FOR IT

which application is:

X the attached application
(for original application)

_____ application Serial No. _____
filed _____, and amended on _____

(for declaration not accompanying application)

that I have reviewed and understand the contents of the specification of the above-identified application, including the claims, as amended by any amendment referred to above; that I acknowledge my duty to disclose information of which I am aware which is material to the patentability of this application under 37 C.F.R. 1.56, that I hereby claim foreign priority benefits under Title 35, United States Code §119, §172 or §365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified on said list any foreign application for patent or inventor's certificate on this invention having a filing date before that of the application on which priority is claimed:

Application Number	Country	Filing Date	Priority Claimed (yes or no)
325445/1998	Japan	November 16, 1998	yes
1772/1999	Japan	January 7, 1999	yes

I hereby claim the benefit of Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in a listed prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge my duty to disclose any information material to the patentability of this application under 37 C.F.R. 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status (patented, pending, abandoned)

I hereby appoint John H. Mion, Reg. No. 18,879; Donald E. Zinn, Reg. No. 19,046; Thomas J. Macpeak, Reg. No. 19,292; Robert J. Seas, Jr., Reg. No. 21,092; Darryl Mexic, Reg. No. 23,063; Robert V. Sloan, Reg. No. 22,775; Peter D. Olexy, Reg. No. 24,513; J. Frank Osha, Reg. No. 24,625; Waddell A. Biggart, Reg. No. 24,861; Robert G. McMorrow, Reg. No. 19,093; Louis Gubinsky, Reg. No. 24,835; Neil B. Siegel, Reg. No. 25,200; David J. Cushing, Reg. No. 28,703; John R. Inge, Reg. No. 26,916; Joseph J. Ruch, Jr., Reg. No. 26,577; Sheldon I. Landsman, Reg. No. 25,430; Richard C. Turner, Reg. No. 29,710; Howard L. Bernstein, Reg. No. 25,665; Alan J. Kasper, Reg. No. 25,426; Kenneth J. Burchfiel, Reg. No. 31,333; Gordon Kit, Reg. No. 30,764; Susan J. Mack, Reg. No. 30,951; Frank L. Bernstein, Reg. No. 31,484; Mark Boland, Reg. No. 32,197; William H. Mandir, Reg. No. 32,156; Scott M. Daniels, Reg. No. 32,562; Brian W. Hannon, Reg. No. 32,778 and Abraham J. Rosner, Reg. No. 33,276, my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and request that all correspondence about the application be addressed to **SUGHRUE, MION, ZINN, MACPEAK & SEAS**, 2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037-3202.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date February 8, 1999

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Ninth Inventor _____

First Name

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Tenth Inventor _____

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Citizenship _____

Date _____

Eleventh Inventor _____

First Name

Middle Initial

Last Name

Residence _____

Signature _____

Post Office Address _____

Citizenship _____

Date _____

Twelfth Inventor _____

First Name

Middle Initial

Last Name

Residence _____

Signature _____

Post Office Address _____

Citizenship _____

Assignment

Whereas, ~~#~~We, NORIO HIRAYAMA, MITSUO OSADA, AKIRA ICHIDA, YOSHINARI AMANO, of
KIYOSHI ASAI, HIDETOSHI MAESATO, TADASHI ARIKAWA and KENJI SAKIMAE
Yamagata, Japan; Yamagata, Japan; Toyama, Japan; Yamagata, Japan;
Toyama, Japan; Yamagata, Japan; Toyama, Japan and Yamagata, Japan; respectively,
hereinafter called assignor(s), have invented certain improvements in

SEMICONDUCTOR PACKAGE AND METHOD FOR PRODUCING HEAT-RADIATING SUBSTRATE FOR IT
and executed an application for Letters Patent of the United States of America therefor on
February 8, 1999 ; and

Whereas, Tokyo Tungsten Co. Ltd.
24-8, Higashiueno 5-chome, Taito-ku, Tokyo, Japan

(assignee), desires to acquire the entire right, title, and interest in the application and invention, and to
any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

~~#~~We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its
successors and assigns, the entire right, title and interest in the application and the invention disclosed
therein for the United States of America, including the right to claim priority under 35 U.S.C. §119, and
~~#~~we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth
in the application to the assignee, its successors and assigns; and ~~#~~we will execute without further
consideration all papers deemed necessary by the assignee in connection with the United States application
when called upon to do so by the assignee.

~~#~~We hereby authorize and request my attorneys SUGHRUE, MION, ZINN, MACPEAK & SEAS of
2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037-3202 to insert here in parentheses (Application
number _____, filed _____) the filing date and application
number of said application when known.

Date: February 8, 1999

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Date: February 8, 1999

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MITSUO OSADA

Date: February 8, 1999

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